

Title (en)

COMPOSITION AND METHOD FOR PRIMING SUBSTRATE MATERIALS

Title (de)

ZUSAMMENSETZUNG UND VERFAHREN ZUR GRUNDIERUNG VON SUBSTRATEN

Title (fr)

COMPOSITION ET PROCEDE PERMETTANT D'APPRETER DES MATERIAUX SUBSTRATS

Publication

EP 1017881 A1 20000712 (EN)

Application

EP 98904927 A 19980130

Priority

- US 9802178 W 19980130
- US 3662797 P 19970131

Abstract (en)

[origin: WO9833951A1] The formulation primes materials used in the processing of substrates. The formulation comprises one or more filming amines which are mixed with and neutralized by an appropriate acid or combination of acids. Water is used as the solvent and a surfactant is optionally added to aid in the cleaning, anti-foaming and wetting of the substrates. Printed circuit boards, chemically milled alloys and chemically plated alloys can be coated with the formulation as a one-step priming method prior to lamination of a resist layer.

IPC 1-7

C23C 22/52; **C23F 1/02**; **C25D 5/02**

IPC 8 full level

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Citation (search report)

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